

Plastics in Electronics Components: Technologies and Global Markets

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Abstracts

Report Scope:

This study covers all electronic components where plastics are used to a significant extent. It concentrates on components produced by injection molding compression molding, and encapsulation. It does not cover wire and cable, films used in capacitors or recording media, or enclosures. The study also identifies major material suppliers and key processors. It reviews important new technologies, as well as changes in legislation and industry standards and norms that may have significant effects on markets for electronic components, and it looks at interpolymer competition.

Report Includes:

61 data tables and 23 additional tables

An overview of the global markets and technologies for plastics in electronics components

Analyses of the global market trends, with data for 2022, 2023 and projections of compound annual growth rates (CAGRs) through 2028

Estimation of the market size and revenue forecast for plastics in electronics components, and market share analysis by type, end-user, and region

Highlights of the market opportunities, and major issues and trends affecting the plastic industry

Insight into the recent industry structure, regulations and policies, pipeline products, and the vendor landscape of the market leading participants

Company profiles of major players within the industry, including BASF, Covestro AG, Henkel AG, Mitsubishi Engineering-Plastics Corp., and SABIC

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ASHLAND INC.

BASF

CELANESE

COVESTRO AG
CYTEC INDUSTRIES INC.
DSM
DUPONT DE NEMOURS AND CO.
EMS GRIVORY
EPIC RESINS
HENKEL AG
HUNTSMAN INTERNATIONAL LLC
INTERPLASTIC CORP.
KINGFA SCIENCE AND TECHNOLOGY CO. LTD.
LANXESS AG
MITSUBISHI ENGINEERING-PLASTICS CORP.
POLYPLASTICS
SABIC INNOVATIVE PLASTICS
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